

**IN THE CLAIMS:**

The following is a complete listing of the claims with an indication of status of each:

1      Claim 1 (Currently Amended). An optical write head comprising a substrate, and a  
2      plurality of light-emitting device array chips arranged on the substrate in a straight line or  
3      in a staggered layout so as to oppose a rod lens array, each of the light-emitting device  
4      array ~~device~~ chips having a light-emitting device array, wherein the rod lens array, a  
5      substrate support member for supporting the substrate, and a driver circuit board are each  
6      secured directly to a support member.

1      Claim 2 (Original). The optical write head according to claim 1, wherein the support  
2      member and the substrate support member are formed from metallic material.

1      Claim 3 (Previously Presented). The optical write head according to claim 1, wherein at  
2      least one frame of the rod lens array to be bonded to said support member is a glass plate.

1      Claim 4 (Original). The optical write head according to claim 1, wherein a plurality of  
2      adhesive injection holes are formed in a surface of the support member with which the  
3      rod lens array is to be brought into contact, the holes being arranged along a longitudinal  
4      direction of the rod lens array and being formed so as to penetrate through the support  
5      member to a reverse side thereof.

1      Claim 5 (Previously Presented). The optical write head according to claim 1, wherein at  
2      least one slit of V-shaped cross section for injecting an adhesive is formed in a portion of  
3      a surface of the support member to be brought into contact with the rod lens array, so as  
4      to extend in the longitudinal direction of the rod lens array, and a plurality of adhesive  
5      injection holes are formed in the at least one slit so as to penetrate through the support  
6      member to a reverse side thereof.

1        Claim 6 (Previously Presented). The optical write head according to claim 1, wherein at  
2        least two positioning pins are provided at predetermined positions on the substrate  
3        support member.

1        Claim 7 (Original). The optical write head according to claim 1, wherein at least two  
2        rotatable eccentric pins penetrating through the support member are provided so as to  
3        come into contact with the substrate support member.

1        Claim 8 (Previously Presented) . A method of adjusting an optical write head comprising  
2        a substrate, and a plurality of light-emitting device array chips arranged on the substrate  
3        in a straight line or in a staggered layout so as to oppose a rod lens array, each of the  
4        light-emitting array device chips having a light-emitting device array, wherein the rod  
5        lens array, a substrate support member for supporting the substrate, and a driver circuit  
6        board are each secured directly to a support member, wherein at least two rotatable  
7        eccentric pins penetrating through the support member are provided so as to come into  
8        contact with the substrate support member, the method comprising the step of rotating the  
9        at least two eccentric pins to thereby move the substrate support member kept in contact  
10       with the eccentric pins and adjust the distance between a light-emission section of the  
11       light-emitting device array and a light-incident end face of the rod lens array.

1        Claim 9 (Currently Amended). A method of optically aligning elements of an optical  
2        write head comprising a substrate, and a plurality of light-emitting device array chips  
3        arranged on the substrate in a straight line or in a staggered layout so as to oppose a rod  
4        lens array, each of the light-emitting array device chips having a light-emitting device  
5        array, the method comprising the steps of securing the rod lens array **by a plurality of**  
6        **adhesive injections**, a substrate support member for supporting the substrate, and a driver  
7        circuit board ~~are each secured directly~~ to a support member, and die-bonding the light-  
8        emitting device array chips to the substrate to a predetermined location on the substrate  
9        support member while being positioned with respect to a reference plane of the substrate

10 support member.

1 Claim 10 (Previously Presented). An optical write head comprising a substrate, and a  
2 plurality of light-emitting device array chips arranged on the substrate in a straight line or  
3 in a staggered layout so as to oppose a rod lens array, each of the light-emitting device  
4 array chips having a light-emitting device array, wherein the light-emitting device array  
5 chips are mounted directly on a flexible printed circuit sheet interposed between the  
6 substrate and the light-emitting device array chips.

1 Claim 11 (Currently Amended). The optical write head according to claim 10, wherein a  
2 reverse surface of a light-emitting device array chip mount section of the flexible printed  
3 circuit sheet is disposed in close contact with **a member said substrate** having rigidity.

1 Claim 12 (Original). The optical write head according to claim 10, wherein the flexible  
2 printed circuit sheet is of multilayer type and interposed between the resin layer and the  
3 copper foil.

1 Claim 13 (Original). The optical write head according to claim 10, wherein the flexible  
2 printed circuit sheet has a thickness of 30 to 50  $\mu\text{m}$ .

1 Claim 14 (Original). The optical write head according to claim 10, wherein the light-  
2 emitting array is a self-scan-type light-emitting array.

1 Claim 15 (Currently Amended). The optical write head according to claim 11, wherein  
2 reference position marks for specifying respective positions at which the light-emitting  
3 array chips are to be arranged are provided on a surface of the **member substrate** which  
4 has rigidity and are disposed in close contact with the flexible printed circuit sheet.

1 Claim 16 (Previously Presented). A method of assembling an optical write head,

2 comprising the steps of:  
3 bonding a portion of a flexible printed circuit sheet to a member having rigidity;  
4 arranging a plurality of light-emitting device array chips at a predetermined  
5 positions on the flexible printed circuit sheet in the form of a straight line or in a  
6 staggered layout and bonding the light-emitting device array chips directly to the flexible  
7 printed circuit sheet on a side of the flexible printed circuit sheet that is opposite the  
8 member having rigidity;  
9 electrically connecting the light-emitting device array chips to predetermined wire  
10 bonding pads provided on the flexible printed circuit sheet by means of wire bonding; and  
11 fixing the member having rigidity at a predetermined position on a support  
12 member having a rod lens array and a light-emitting device array drive circuit board  
13 mounted thereon beforehand with light emitting device array chips opposing said rod lens  
14 array.

1 Claim 17 (Original). An optical write head comprising a flexible circuit sheet remaining  
2 in close contact with a member having rigidity, and a plurality of light-emitting device  
3 array chips arranged on the flexible circuit sheet in a straight line or in a staggered layout  
4 so as to oppose a gradient index rod lens array, each of the light-emitting array chips  
5 having a light-emitting device array, wherein the member having rigidity is a metallic  
6 member substantially equal in coefficient of thermal expansion to the rod lens array.

1 Claim 18 (Currently Amended). An optical write head comprising a flexible circuit sheet  
2 remaining in close contact with a member having rigidity, and a plurality of light-emitting  
3 device array chips arranged on the flexible circuit sheet in a straight line or in a staggered  
4 layout so as to oppose a gradient index rod lens array, each **of the light-emitting array**  
5 **chips having a light-emitting device** array, wherein the member having rigidity is a  
6 metallic member substantially equal in coefficient of thermal expansion to the light-  
7 emitting device array chips.

1        Claim 19 (Previously Presented). The optical write head according to claim 17, wherein  
2        a frame of the rod lens array is formed from glass, and the metallic member is a nickel  
3        alloy or titanium.

1        Claim 20 (Previously Presented). The optical write head according to claim 17, wherein  
2        the light-emitting device array is a self-scan-type light-emitting device array.

1        Claim 21 (Original). An optical write head comprising:  
2                a support member having first and second reference planes;  
3                a gradient index rod lens array having gradient index rod lenses arrayed in at least  
4        one row and a frame that supports the rod lenses and that is fixed to the first reference  
5        plane;  
6                a substrate support member fixed to the second reference plane;  
7                a flexible printed circuit substrate fixed to the substrate support member; and  
8                a plurality of self-scanning, light-emitting device array chips that are provided to  
9        the flexible printed circuit substrate and that have light-emitting devices optically aligned  
10       with respect to the respective gradient index rod lenses.

1        Claim 22 (Original). The optical write head according to claim 21, wherein the first  
2        reference plane is flush with the second reference plane.

1        Claim 23 (Original). The optical write head according to claim 21, wherein the first  
2        reference plane is parallel to the second reference plane.

1        Claim 24 (Original). The optical write head according to claim 21, wherein each of the  
2        support member and the substrate support member is made of metal.

1        Claim 25 (Original). The optical write head according to claim 21, wherein the frame is  
2        made of glass.

1      Claim 26 (Original). The optical write head according to claim 21, wherein the light-  
2      emitting device array chips are fixed to the flexible printed circuit substrate after the  
3      flexible printed circuit substrate is fixed to the substrate support member.

1      Claim 27 (Original). The optical write head according to claim 26, wherein the substrate  
2      support member is substantially equal in coefficient of thermal expansion to the light-  
3      emitting array chips.

1      Claim 28 (Original). The optical write head according to claim 21, wherein the substrate  
2      support member is substantially equal in coefficient of thermal expansion to the gradient  
3      index rod lens array.

1      Claim 29 (Original). An optical printer comprising:  
2          a photosensitive drum;  
3          the optical write head constructed according to claim 21 and arranged around the  
4          photosensitive drum so that the gradient index rod lenses are confronted with the  
5          photosensitive drum;  
6          an electrostatic charger arranged around the photosensitive drum;  
7          a development unit arranged around the photosensitive drum;  
8          a transfer unit arranged around the photosensitive drum; and  
9          a fixing unit arranged downstream of the transfer unit with respect to a paper  
10      feeding direction.

1      Claim 30 (Previously Presented). The optical write head according to claim 18, wherein  
2      a frame of the rod lens array is formed from glass, and the metallic member is nickel alloy  
3      or titanium.

1      Claim 31 (Previously Presented). The optical write head according to claim 18, wherein  
2      the light-emitting device array is a self-scan-type light-emitting device array.